



PATENT
5298-03500/PM99021

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Lau

Serial No. 09/476,669

Filed: December 30, 1999

For: METHOD FOR FORMING A
METALLIZATION STRUCTURE IN
AN INTEGRATED CIRCUIT

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Group Art Unit: 1753

Examiner: Cantelmo, G.

Atty. Dkt. No. 5298-03500

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TC 1700 # A
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I hereby certify that this correspondence is being deposited
with the U.S. Postal Service with sufficient postage as First
Class Mail in an envelope addressed to: Box: Non-Fee
Amendment, Commissioner for Patents, Washington, D.C.
20231, on the date indicated below:

July 12, 2001
Date

Kevin L. Daffer

AMENDMENT; RESPONSE TO OFFICE ACTION DATED MARCH 12, 2001

Box: Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Dear Sir/ Madam:

This paper is submitted in response to the Office Action dated March 12, 2001 to further
highlight reasons why the application is in condition for allowance.

Please amend the case as follows:

In the Specification:

07/27/2001 WMITCHEL 00000006 501505 09476669

01 FC:102
02 FC:103

80.00 CH
144.00 CH

Please replace pg. 13, lines 10-22, with the amended paragraph below. A "marked-up"
version of each amendment is included in Attachment A.